

Update Search

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L12	729	late adj transition near3 metal\$1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/16 12:58
L13	63870	noble adj metal\$1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/16 12:58
L14	8560076	(Ru Rh Pd Ag Os Ir Pt Au) (Ruthenium Rhodium Palladium Silver Osmium iridium platinum gold)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/16 12:58
L15	10531	ferromagnetic adj metal\$1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/16 12:58
L16	9578140	(Co Ni Fe) (cobalt nickel iron)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/16 12:58
L17	566365	(SiN BN AlN) ((silicon boron aluminum) near3 nitride)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/16 12:58
L18	199615	(L12 L13 L14 L15 L16) same L17	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/16 12:58
L19	88007	L18 same (flex\$5 movable mov\$3 elastic\$5 bend\$5 beam\$1 cantilever\$1 hinge\$1)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/16 13:11

L20	884	L19 and (MEMS micro adj2 mechanical)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/16 12:58
L21	716	L20 and (sens\$4 actuat\$4 (micro adj mirror\$1))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/16 13:23
L25	27	L21 and ternary	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/16 13:09
L29	526	(257/415).CCLS.	US-PGPUB; USPAT	OR	OFF	2005/10/16 13:36
L30	594	(257/417).CCLS.	US-PGPUB; USPAT	OR	OFF	2005/10/16 13:36
L31	399	(257/419).CCLS.	US-PGPUB; USPAT	OR	OFF	2005/10/16 13:36
L32	187	(257/254).CCLS.	US-PGPUB; USPAT	OR	OFF	2005/10/16 13:36

Interference Search

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L27	18	((flex\$5 movable mov\$3 elastic\$5 bend\$5 beam\$1 cantilever\$1 hinge\$1) same ternary).clm.	US-PGPUB	OR	OFF	2005/10/16 13:11

Day : Sunday
Date: 10/16/2005


PALM INTRANET

Time: 14:08:37

Inventor Name Search Result

Your Search was:

Last Name = REID

First Name = JASON

Application#	Patent#	Status	Date Filed	Title	Inventor Name
<u>08283454</u>	<u>5622893</u>	150	08/01/1994	METHOD OF FORMING CONDUCTIVE NOBLE-METAL-INSULATOR-ALLOY BARRIER LAYER FOR HIGH-DIELECTRIC-CONSTANT MATERIAL ELECTRODES	REID, JASON
<u>08473464</u>	<u>5729054</u>	150	06/07/1995	CONDUCTIVE NOBLE-METAL-INSULATOR-ALLOY BARRIER LAYER FOR HIGH-DIELECTRIC-CONSTANT MATERIAL ELECTRODES	REID, JASON
<u>08487197</u>	<u>5696018</u>	150	06/07/1995	METHOD FORMING CONDUCTIVE NOBLE-METAL-INSULATOR-ALLOY BARRIER LAYER FOR HIGH-DIELECTRIC-CONSTANT MATERIAL ELECTRODES	REID, JASON
<u>09637479</u>	<u>6396619</u>	150	08/11/2000	DEFLECTABLE SPATIAL LIGHT MODULATOR HAVING STOPPING MECHANISMS	REID, JASON
<u>10796286</u>	Not Issued	20	03/10/2004	Method of forming low-k dielectrics	REID, JASON
<u>10886061</u>	Not Issued	30	07/08/2004	Dielectric materials and methods for integrated circuit applications	REID, JASON
<u>60395418</u>	Not Issued	159	07/13/2002	Photosensitive hybrid organic-inorganic dielectric materials for integrated circuit applications	REID, JASON
<u>60414578</u>	Not Issued	159	09/27/2002	Materials and methods for forming hybrid organic-inorganic dielectric materials for integrated circuit applications	REID, JASON
<u>60504992</u>	Not Issued	159	09/23/2003	Method of forming low-k-dielectrics	REID, JASON
<u>60385620</u>	Not	159	06/04/2002	Application of fluorinated phenyl	REID, JASON

	Issued			silanes as anti-stiction protective coatings	R.
<u>09910537</u>	Not Issued	71	07/20/2001	Transition metal dielectric alloy materials for MEMS	REID, JASON S.
<u>10167272</u>	<u>6958123</u>	150	06/10/2002	METHOD FOR REMOVING A SACRIFICIAL MATERIAL WITH A COMPRESSED FLUID	REID, JASON S.
<u>10176478</u>	Not Issued	71	06/21/2002	MEMS with flexible portions made of novel materials	REID, JASON S.
<u>10198389</u>	Not Issued	71	07/17/2002	MEMS device made of transition metal-dielectric oxide materials	REID, JASON S.
<u>10346449</u>	Not Issued	94	01/17/2003	SEMICONDUCTOR DEVICE	REID, JASON S.
<u>10346450</u>	Not Issued	41	01/17/2003	Integrated circuits having organic-inorganic dielectric materials and methods for forming such integrated circuits	REID, JASON S.
<u>10346451</u>	Not Issued	93	01/17/2003	MATERIALS AND METHODS FOR FORMING HYBRID ORGANIC-INORGANIC DIELECTRIC MATERIALS FOR INTEGRATED CIRCUIT APPLICATIONS	REID, JASON S.
<u>10346539</u>	Not Issued	30	01/17/2003	Poly(organosiloxane) materials and methods for hybrid organic-inorganic dielectrics for integrated circuit applications	REID, JASON S.
<u>10402777</u>	<u>6960305</u>	150	03/28/2003	METHODS FOR FORMING AND RELEASING MICROELECTROMECHANICAL STRUCTURES	REID, JASON S.
<u>10453933</u>	Not Issued	41	06/04/2003	Materials and methods for forming hybrid organic-inorganic anti-stiction materials for micro-electromechanical systems	REID, JASON S.
<u>11041834</u>	Not Issued	20	01/24/2005	Method for removing a sacrificial material with a compressed fluid	REID, JASON S.
<u>60228007</u>	Not Issued	159	08/23/2000	Transition metal-dielectric alloys for flexible beams and hinges in micro-electromechanical systems	REID, JASON S.
<u>60298529</u>	Not Issued	159	06/15/2001	Method for removing a sacrificial material with a compressed fluid	REID, JASON S.
<u>60300533</u>	Not Issued	159	06/23/2001	MEMS with flexible portions made of novel materials	REID, JASON S.
<u>60349955</u>	Not Issued	159	01/17/2002	Application of photosensitive fluorinated hybrid organosiloxane	REID, JASON S.

				materials for integrated circuit applications	
--	--	--	--	---	--

Inventor Search Completed: No Records to Display.

Search Another: Inventor

Last Name	First Name	
<input type="text" value="Reid"/>	<input type="text" value="Jason"/>	<input type="button" value="Search"/>

To go back use Back button on your browser toolbar.

Back to [PALM](#) | [ASSIGNMENT](#) | [OASIS](#) | [Home page](#)